

**Listing of All Claims Including Current Amendments**

- 1-3. (cancelled)
4. (currently amended) The image pick-up module of Claim 24, wherein said first leg and said second leg ~~two legs~~ of said V-shaped third section extend along a straight-line prolongation of said first and said second sections, respectively.
- 5-6. (cancelled)
7. (withdrawn – previously presented) The image pick-up module of Claim 24, wherein said at least one cable is bonded to an inner surface of the circuit board.
8. (previously presented) The image pick-up module of Claim 24, wherein said at least one cable is bonded to an outer surface of said circuit board.
9. (cancelled)
10. (withdrawn – previously presented) The image pick-up module of Claim 24, wherein said third section comprises at least one passage for said at least one cable leading away from said circuit board.
11. (withdrawn) The image pick-up module of Claim 10, wherein said at least one passage is configured as a marginal recess in said third section.
12. (withdrawn – previously presented) The image pick-up module of Claim 24, wherein said third section comprises at least one passage for said at least one cable leading away from said circuit board, wherein said at least one passage is configured as a substantially central opening in said third section.
13. (previously presented) The image pick-up module of Claim 24, wherein the interior of said circuit board is filled with an electrically non-conductive feeling compound.

14. (previously presented) The image pick-up module of Claim 24, wherein said circuit board comprises a forth section arranged opposite said third section and accommodating said image sensor on its outer surface.

15. (previously presented) The image pick-up module of Claim 14, wherein said forth section further comprises at least one of an electric component and at least one electric circuit-board conductor.

16. (cancelled)

17. (previously presented) The image pick-up module of Claim 24, wherein said circuit board is provided on its outer surface with recesses for bonding of said image sensor.

18. (previously presented) The image pick-up module of Claim 24, wherein said third section of said circuit board further comprises at least one contact for bonding said cable leading away from said circuit board.

19. (previously presented) The image pick-up module of Claim 24, wherein said third section of said circuit board further comprises at least one electric circuit-board conductor for electrically connecting said first section and said second section.

20. (cancelled)

21. (previously presented) The image pick-up module of Claim 24, wherein said first section and said second section of said board blank are flexibly connected via an additional section, but are arranged in spaced relationship at one and the same level, wherein said first section and said second section each serve for bonding said at least one cable, and wherein said third section is flexibly connected to said additional section on an end face of said additional section.

22-23. (cancelled)

24. (currently amended) Image pick-up module, comprising:

an endoscope shaft having a longitudinal axis;

an electronic image sensor including an image pick-up surface transverse to the longitudinal axis of said shaft, said image sensor having contact fingers;

a circuit board electrically bonded to said image sensor, said circuit board comprising

first and second sections, said first and second sections each having a first end bonded to said image sensor and a second end, wherein said first and second sections extend longitudinally from said image sensor substantially perpendicular to the image pick-up surface of said sensor and substantially in parallel to one other, wherein said contact fingers are electrically bonded to said first section and to said second section; and

a third section having a substantially V-shaped configuration integrally formed with the second end of said second section, said third section having a first leg and a second leg, said first and second legs extending obliquely to said first and second sections;

at least one cable electrically bonded to said circuit board and leading away from said circuit board, wherein said at least one cable being electrically bonded to said first and second legs.

25. (cancelled)